

ESD SMD Comm COG, Ceramic, 4700 pF, 5%, 200 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805



**Dimensions**

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.9mm +/-0.10mm
S	0.75mm MIN
B	0.5mm +/-0.25mm

**Packaging Specifications**

Packaging:	T&R, 330mm, Paper Tape
Packaging Quantity:	15000

**General Information**

Series:	ESD SMD Comm COG
Style:	SMD Chip
Description:	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features:	Temperature Stable, Low ESR, Class I
RoHS:	Yes
Termination:	Tin
Marking:	No
AEC-Q200:	No
Component Weight:	13 mg
Shelf Life:	78 Weeks
MSL:	1

**Specifications**

Capacitance:	4700 pF
Measurement Condition:	1 kHz 1.0Vrms
Capacitance Tolerance:	5%
Voltage DC:	200 VDC
ESD Level per AEC-Q200:	25,000 V ESD Level
Dielectric Withstanding Voltage:	500 VDC
Temperature Range:	-55/+125°C
Temperature Coefficient:	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC):	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor:	0.1% 1 kHz 1.0Vrms
Aging Rate:	0% Loss/Decade Hour
Insulation Resistance:	100 GOhms